

单电源、轨到轨运算放大器 *MicroAmplifier*™

 查询样品: [OPA2340-DIE](#)

特性

- 轨到轨输入
- 轨到轨输出
- 宽带宽
- 高转换率
- 低总谐波失真 (THD) + 噪声
- 低静态电流
- 单路、双路和四路版本

应用范围

- 驱动模数 (A/D) 转换器
- PCMCIA 卡
- 数据采集
- 过程控制
- 音频处理
- 通信
- 有源滤波器
- 测试设备

说明

OPA2340-DIE 轨到轨 CMOS 运算放大器针对低压、单电源运行进行了优化。轨到轨输入/输出和高速运行使得它们非常适合于驱动采样模数 (A/D) 转换器。OPA2340-DIE 也非常适合于通用和音频应用，也可在数模 (D/A) 转换器的输出上提供 I/V 转换。为了使设计更加灵活，单路、双路和四路版本均具有相同的技术规格。

OPA2340-DIE 由单电源供电运行。双路和四路设计特有完全独立的电路，以大大降低串扰，并且避免干扰。

ORDERING INFORMATION⁽¹⁾

| PRODUCT | PACKAGE DESIGNATOR | PACKAGE | ORDERABLE PART NUMBER | PACKAGE QUANTITY |
|---------|--------------------|--|-----------------------|------------------|
| OPA2340 | TD | Bare die in waffle pack ⁽²⁾ | OPA2340TDF1 | 100 |
| | | | OPA2340TDF2 | 10 |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

BARE DIE INFORMATION

| DIE THICKNESS | BACKSIDE FINISH | BACKSIDE POTENTIAL | BOND PAD METALLIZATION COMPOSITION | BOND PAD THICKNESS |
|---------------|------------------------|--------------------|------------------------------------|--------------------|
| 10.5 mils. | Silicon with backgrind | Floating | AlSiCu | 800 nm |

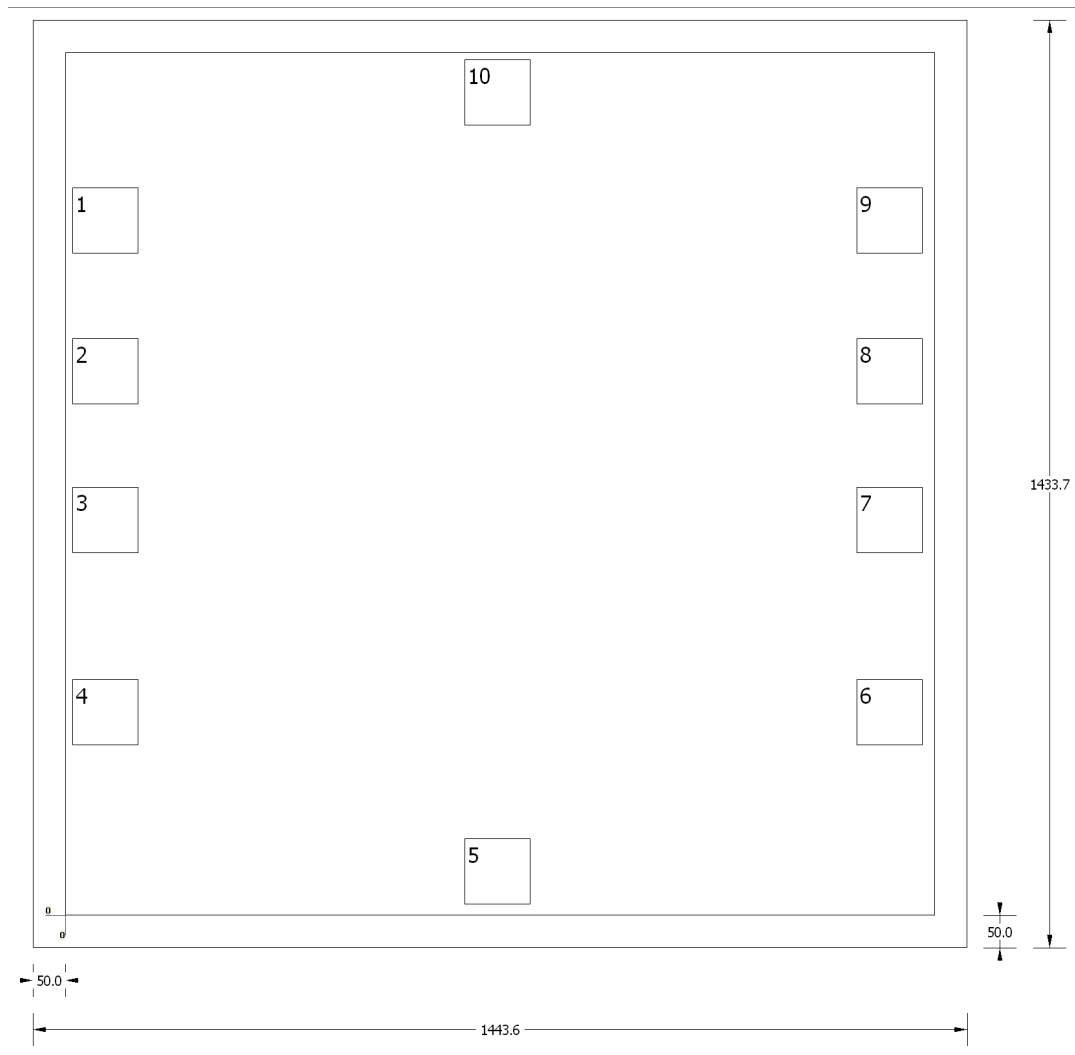


Table 1. Bond Pad Coordinates in Microns

| DESCRIPTION | PAD NUMBER | X MIN | Y MIN | X MAX | Y MAX |
|-------------|------------|-------|---------|-------|---------|
| Out A | 1 | 5 | 1010.65 | 107 | 1112.65 |
| N/C | 2 | 5 | 778.4 | 107 | 880.4 |
| -In A | 3 | 5 | 548.5 | 107 | 650.5 |
| +In A | 4 | 5 | 250.6 | 107 | 352.6 |
| V- | 5 | 611 | 5 | 713 | 107 |
| +In B | 6 | 1217 | 250.6 | 1319 | 352.6 |
| -In B | 7 | 1217 | 548.5 | 1319 | 650.5 |
| N/C | 8 | 1217 | 778.4 | 1319 | 880.4 |
| Out B | 9 | 1217 | 1010.65 | 1319 | 1112.65 |
| V+ | 10 | 611 | 1208.9 | 713 | 1310.9 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| OPA2340TDF1 | ACTIVE | | | 0 | 100 | RoHS & Green | Call TI | N / A for Pkg Type | 25 to 25 | | Samples |
| OPA2340TDF2 | ACTIVE | | | 0 | 10 | RoHS & Green | Call TI | N / A for Pkg Type | 25 to 25 | | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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